

TECHNICAL REPORT



Process management for avionics – Electronic components capability in operation – Part 1: Temperature uprating

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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CONTENTS

FOREWORD	5
INTRODUCTION	2
1 Scope	8
2 Normative references	8
3 Terms, definitions and abbreviated terms	8
3.1 Terms and definitions	8
3.2 Abbreviated terms	12
4 Selection provisions	12
4.1 General	12
4.2 Device selection, usage and alternatives	15
4.2.1 General	15
4.2.2 Alternatives	15
4.2.3 Device technology	15
4.2.4 Compliance with the electronic component management plan	16
4.3 Device capability assessment	16
4.3.1 General	16
4.3.2 Device package and internal construction capability assessment	16
4.3.3 Risk assessment (assembly level)	16
4.3.4 Device uprating methods	17
4.3.5 Device reliability assurance	18
4.4 Device quality assurance (QA) in over wider temperature ranges	19
4.4.1 General Decision for the optimum QA method	19
Device parameter re-characterisation testing	
Device parameter conformance testing	
4.4.2 Device level testing	20
4.4.3 Higher level assembly testing	20
4.5 QA process	20
4.5.1 General	20
4.5.2 Semiconductor device change monitoring	21
4.5.3 Failure data collection and analysis	21
4.6 Final electronic equipment assurance	21
4.7 Documentation and identification	21
4.7.1 Documentation	21
4.7.2 Device identification	22
4.7.3 Customer notification	22
Annex A (informative) Device parameter re-characterisation	24
A.1 Glossary of symbols	24
A.2 Rationale for parameter re-characterisation	25
A.2.1 General	25
A.2.2 Assessment for uprateability	26
A.3 Capability assurance	26
A.3.1 Description	26
A.3.2 Parameter re-characterisation process	26
A.3.3 Application capability assessment	32
A.4 Quality assurance	32
A.5 Factors to be considered in parameter re-characterisation	33

A.6	Report form for documenting device parameter re-characterisation	35
Annex B (informative)	Stress balancing	37
B.1	General	37
B.2	Glossary of symbols	37
B.3	Stress balancing	37
B.3.1	General	37
B.3.2	Determine the ambient temperature extremes	38
B.3.3	Determine parameter relationship to power dissipation	38
B.3.4	Determine the dissipated power versus ambient temperature relationship	38
B.3.5	Assess applicability of the method	40
B.3.6	Determine the new parameter values	40
B.3.7	Conduct parametric and functional tests	41
B.4	Application example	41
B.4.1	General	41
B.4.2	Determine the ambient temperature extremes	42
B.4.3	Select the parameters that can be derated	42
B.4.4	Construct an Iso- T_J plot	43
B.4.5	Determine whether or not the device can be uprated	43
B.4.6	Determine the new parameter values	43
B.4.7	Conduct parametric and functional tests	44
B.5	Other notes	44
B.5.1	Margins	44
B.5.2	Cautions and limitations	44
Annex C (informative)	Parameter conformance assessment	47
C.1	General	47
C.2	Test plan	47
C.2.1	General	47
C.2.2	Critical parameters	47
C.2.3	Minimum allowable test margins	47
C.2.4	Test options	48
C.2.5	Quality assurance	51
Annex D (informative)	Higher assembly level testing	54
D.1	General	54
D.2	Process	54
D.2.1	General	54
D.2.2	Analysis of assembly test definition	54
D.2.3	Perform assembly test	54
D.2.4	Document results	55
D.2.5	Maintenance notification	55
Bibliography	57
Figure 1	– Flow chart for semiconductor devices over wider temperature ranges	14
Figure 2	– Report form for documenting device usage in over wider temperature ranges	23
Figure A.1	– Parameter re-characterisation	25
Figure A.2	– Flow diagram of parameter re-characterisation capability assurance process	28

Figure A.3 – Margin in electrical parameter measurement based on the results of the sample test	31
Figure A.4 – Schematic diagram of parameter limit modifications	32
Figure A.5 – Parameter re-characterisation device quality assurance	33
Figure A.6 – Schematic of outlier products that may can invalidate sample testing.....	34
Figure A.7 – Example of intermediate peak of an electrical parameter: Voltage feedback input threshold change for Motorola MC34261 power factor controller, see [4]	35
Figure A.8 – Report form for documenting device parameter re-characterisation	36
Figure B.1 – Iso- T_J curve: Relationship between ambient temperature and dissipated power	39
Figure B.2 – Graph of electrical parameters versus dissipated power.....	41
Figure B.3 – Iso- T_J curve for the Fairchild MM74HC244	43
Figure B.4 – Power versus frequency curve for the Fairchild MM74HC244	44
Figure B.5 – Flow chart for stress balancing	45
Figure B.6 – Report form for documenting stress balancing	46
Figure C.1 – Relationship of temperature ratings, requirements and margins	48
Figure C.2 – Typical fallout distribution versus $T_{req-max}$	50
Figure C.3 – Parameter conformance assessment flow	52
Figure C.4 – Report form for documenting parameter conformance testing	53
Figure D.1 – Flow chart of higher level assembly testing	55
Figure D.2 – Report form for documenting higher level assembly test at temperature extremes.....	56
Table A.1 – Example of sample size calculation	29
Table A.2 – Parameter re-characterisation example: SN74ALS244 octal buffer/driver	32

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PROCESS MANAGEMENT FOR AVIONICS – ELECTRONIC COMPONENTS CAPABILITY IN OPERATION –

Part 1: Temperature uprating

FOREWORD

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This redline version of the official IEC Standard allows the user to identify the changes made to the previous edition. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in strikethrough red text.

The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC TR 62240-1, which is a Technical Report, has been prepared by IEC technical committee 107: Process management for avionics.

This second edition cancels and replaces the first edition published in 2013. This edition constitutes a technical revision. This edition includes the following significant technical changes with respect to the previous edition:

- a) Revised the wording in 4.1 and the corresponding Figure 1 to reflect current industry practices.

The text of this Technical Report is based on the following documents:

CDTR	Report on voting
107/313/DTR	107/322/RVDTR

Full information on the voting for the approval of this Technical Report can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62240 series, published under the general title *Process management for avionics – Electronic components capability in operation*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
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- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

Traditionally, industries that produced electronic equipment for ADHP (aerospace, defence and high performance) applications have relied on the military specification system for semiconductor device standards and upon manufacturers of military-specified devices as device sources. This assured the availability of semiconductor devices specified to operate over the temperature ranges required for electronic equipment in ADHP applications. In the past, several device manufacturers have exited the military market, resulting in the decreased availability of devices specified to operate over wide temperature ranges. Following are some typical ambient temperature ranges at which devices are marketed:

Military:	–55 °C to + 125 °C
Automotive:	–40 °C to + 125 °C
Industrial:	–40 °C to + 85 °C
Commercial:	0 °C to + 70 °C

If there are no reasonable or practical alternatives, then a potential response is for **electronic** equipment manufacturers to use devices at temperature ranges that are wider than those specified by the device manufacturer.

This document provides information on selecting semiconductor devices, assessing their capability to operate, and assuring their intended quality in the wider temperature ranges. It also reports the need for documentation of such usage.

This can be supported by exchanging technical information with the original device manufacturer.

Operation of the device beyond the manufacturer's limits ~~may~~ **can** result normally in loss of warranty by the device manufacturer.

PROCESS MANAGEMENT FOR AVIONICS – ELECTRONIC COMPONENTS CAPABILITY IN OPERATION –

Part 1: Temperature uprating

1 Scope

This part of IEC 62240, which is a technical report, provides information when using semiconductor devices in wider temperature ranges than those specified by the device manufacturer. The uprating solutions described herein are considered exceptions, when no reasonable alternatives are available; otherwise devices are utilized within the manufacturers' specifications.

The terms “uprating” and “thermal uprating” are being used increasingly in avionics industry discussions and meetings, and clear definitions are included in Clause 3. They were coined as shorthand references to a special case of methods commonly used in selecting electronic components for circuit design.

This document describes the methods and processes for implementing this special case of thermal uprating. All of the elements of these methods and processes employ existing, commonly used best engineering practices. No new or unique engineering knowledge is needed to follow these processes, only a rigorous application of the overall approach.

Even though the device is used at wider temperatures, the wider temperatures usage will be limited to those that do not compromise applications performance and reliability, particularly for devices with narrow feature size geometries (for example, 90 nm and less). This document does not imply that applications use the device to function beyond the absolute maximum rating limits ~~of the device~~ specified by the original device manufacturer and assumes that:

- device usage outside the original device manufacturers' specified temperature ranges is done only when no reasonable alternative approach is available and is performed with appropriate justification;
- if it is necessary to use devices outside the original device manufacturers' specified temperature ranges, it is done with documented and controlled processes that assure integrity of the electronic equipment.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TS 62239-1, *Process management for avionics – Management plan – Part 1: Preparation and maintenance of an electronic components management plan*

TECHNICAL REPORT



Process management for avionics – Electronic components capability in operation – Part 1: Temperature uprating

CONTENTS

FOREWORD	5
INTRODUCTION	7
1 Scope	8
2 Normative references	8
3 Terms, definitions and abbreviated terms	8
3.1 Terms and definitions	8
3.2 Abbreviated terms	12
4 Selection provisions	12
4.1 General	12
4.2 Device selection, usage and alternatives	14
4.2.1 General	14
4.2.2 Alternatives	14
4.2.3 Device technology	14
4.2.4 Compliance with the electronic component management plan	15
4.3 Device capability assessment	15
4.3.1 General	15
4.3.2 Device package and internal construction capability assessment	15
4.3.3 Risk assessment (assembly level)	15
4.3.4 Device uprating methods	16
4.3.5 Device reliability assurance	17
4.4 Device quality assurance (QA) over wider temperature ranges	18
4.4.1 Decision for the optimum QA method	18
4.4.2 Device level testing	19
4.4.3 Higher level assembly testing	19
4.5 QA process	19
4.5.1 General	19
4.5.2 Semiconductor device change monitoring	19
4.5.3 Failure data collection and analysis	19
4.6 Final electronic equipment assurance	20
4.7 Documentation and identification	20
4.7.1 Documentation	20
4.7.2 Device identification	20
4.7.3 Customer notification	20
Annex A (informative) Device parameter re-characterisation	22
A.1 Glossary of symbols	22
A.2 Rationale for parameter re-characterisation	23
A.2.1 General	23
A.2.2 Assessment for uprateability	23
A.3 Capability assurance	24
A.3.1 Description	24
A.3.2 Parameter re-characterisation process	24
A.3.3 Application capability assessment	29
A.4 Quality assurance	30
A.5 Factors to be considered in parameter re-characterisation	30
A.6 Report form for documenting device parameter re-characterisation	32
Annex B (informative) Stress balancing	34

B.1	General.....	34
B.2	Glossary of symbols.....	34
B.3	Stress balancing	34
B.3.1	General	34
B.3.2	Determine the ambient temperature extremes.....	35
B.3.3	Determine parameter relationship to power dissipation	35
B.3.4	Determine the dissipated power versus ambient temperature relationship.....	35
B.3.5	Assess applicability of the method	37
B.3.6	Determine the new parameter values	37
B.3.7	Conduct parametric and functional tests	38
B.4	Application example.....	38
B.4.1	General	38
B.4.2	Determine the ambient temperature extremes.....	39
B.4.3	Select the parameters that can be derated.....	39
B.4.4	Construct an Iso- T_J plot.....	40
B.4.5	Determine whether or not the device can be uprated	40
B.4.6	Determine the new parameter values	40
B.4.7	Conduct parametric and functional tests	41
B.5	Other notes.....	41
B.5.1	Margins	41
B.5.2	Cautions and limitations.....	41
Annex C (informative)	Parameter conformance assessment.....	44
C.1	General.....	44
C.2	Test plan.....	44
C.2.1	General	44
C.2.2	Critical parameters	44
C.2.3	Minimum allowable test margins	44
C.2.4	Test options.....	45
C.2.5	Quality assurance.....	48
Annex D (informative)	Higher assembly level testing.....	51
D.1	General.....	51
D.2	Process	51
D.2.1	General	51
D.2.2	Analysis of assembly test definition	51
D.2.3	Perform assembly test	51
D.2.4	Document results.....	52
D.2.5	Maintenance notification	52
Bibliography	54
Figure 1	– Flow chart for semiconductor devices over wider temperature ranges	13
Figure 2	– Report form for documenting device usage over wider temperature ranges	21
Figure A.1	– Parameter re-characterisation.....	23
Figure A.2	– Flow diagram of parameter re-characterisation capability assurance process.....	25
Figure A.3	– Margin in electrical parameter measurement based on the results of the sample test.....	28
Figure A.4	– Schematic diagram of parameter limit modifications.....	29

Figure A.5 – Parameter re-characterisation device quality assurance	30
Figure A.6 – Schematic of outlier products that can invalidate sample testing	31
Figure A.7 – Example of intermediate peak of an electrical parameter: Voltage feedback input threshold change for Motorola MC34261 power factor controller, see [4]	32
Figure A.8 – Report form for documenting device parameter re-characterisation	33
Figure B.1 – Iso- T_J curve: Relationship between ambient temperature and dissipated power	36
Figure B.2 – Graph of electrical parameters versus dissipated power	38
Figure B.3 – Iso- T_J curve for the Fairchild MM74HC244	40
Figure B.4 – Power versus frequency curve for the Fairchild MM74HC244	41
Figure B.5 – Flow chart for stress balancing	42
Figure B.6 – Report form for documenting stress balancing	43
Figure C.1 – Relationship of temperature ratings, requirements and margins	45
Figure C.2 – Typical fallout distribution versus $T_{req-max}$	47
Figure C.3 – Parameter conformance assessment flow	49
Figure C.4 – Report form for documenting parameter conformance testing	50
Figure D.1 – Flow chart of higher level assembly testing	52
Figure D.2 – Report form for documenting higher level assembly test at temperature extremes	53
Table A.1 – Example of sample size calculation	26
Table A.2 – Parameter re-characterisation example: SN74ALS244 octal buffer/driver	29

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COMPONENTS CAPABILITY IN OPERATION –****Part 1: Temperature uprating****FOREWORD**

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